

# SPECIFICATION AGM 24064A-802

Atualizado pelo MKT em 10/06/2015

	AGTechnolog	gies	MODLE NO: AGM 24064A-802		
REC	ORDS OF REV	<b>ISION</b>	DOC. FIRST ISSUE		
VERSION	DATE	REVISED PAGE NO.	SUMMARY		
0	2009/11/24		First issue		
Α	2010/04/26		Modify IC=RA6963		
В	2012/10/16		Modify backlight		
			information.		
С	2013/05/20		Remove IC information		

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## **1.Precautions in use of LCD Modules**

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) AGT have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9)AGT have the right to change the PCB Rev.(In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, AGT have the right to modify the version.)

# **2.General Specification**

Item	Dimension	Unit
Number of dots	240 x 64	_
Module dimension	180.0 x 65.0 x 12.3 (MAX)	mm
View area	133.0 x 39.0	mm
Active area	127.16 x 33.88	mm
Dot size	0.49 x 0.49	mm
Dot pitch	0.53 x 0.53	mm
LCD type	STN Negative, Blue Transmissive (In LCD production, It will occur slightly color can only guarantee the same color in the same ba	
Duty	1/64	
View direction	6 o'clock	
Backlight Type	LED White	
IC	RA6963	

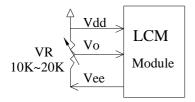
## **3.Absolute Maximum Ratings**

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T <sub>OP</sub>	-20	_	+70	°C
Storage Temperature	T <sub>ST</sub>	-30	_	+80	°C
Input Voltage	V <sub>IN</sub>	-0.3	_	V <sub>DD</sub> +0.3	V
Supply Voltage For Logic	VDD-V <sub>SS</sub>	-0.3	_	+7.0	V

# **4.Electrical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$V_{DD}$ - $V_{SS}$		3.0	_	5.5	V
		Ta=-20°C	_		13.9	V
Supply Voltage For LCD	$V_{DD}$ - $V_0$	Ta=25℃	12.1	12.5	12.9	V
*Note		Ta=70°C	10.1			V
Input High Volt.	V <sub>IH</sub>		0.8Vdd		V <sub>DD</sub>	V
Input Low Volt.	V <sub>IL</sub>		0	_	$0.2 V_{DD}$	V
Output High Volt.	V <sub>OH</sub>	_	VDD-0.3		V <sub>DD</sub>	V
Output Low Volt.	V <sub>OL</sub>	_	0		0.3	V
Supply Current	I <sub>DD</sub>	_	12	16	20	mA

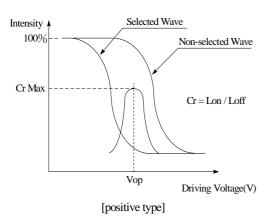
\* Note: Please design the VOP adjustment circuit on customer's main board



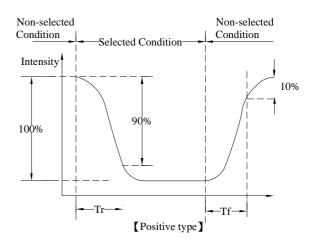
# **5.Optical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
	heta	$CR \ge 2$	0	_	20	$\phi = 180^{\circ}$
	θ	$CR \ge 2$	0	_	40	$\phi = 0^{\circ}$
View Angle	θ	$CR \ge 2$	0	_	30	$\phi = 90^{\circ}$
	θ	$CR \ge 2$	0	_	30	$\phi = 270^{\circ}$
Contrast Ratio	CR	_		3		
Despense Time	T rise	_		150	200	ms
Response Time	T fall	—		150	200	ms

#### **Definition of Operation Voltage (Vop)**



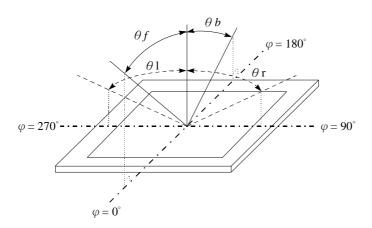
Definition of Response Time ( Tr , Tf )



**Conditions :** 

Operating Voltage : Vop Frame Frequency : 64 HZ Viewing Angle( $\theta$ ,  $\phi$ ): 0°, 0° Driving Waveform: 1/N duty, 1/a bias

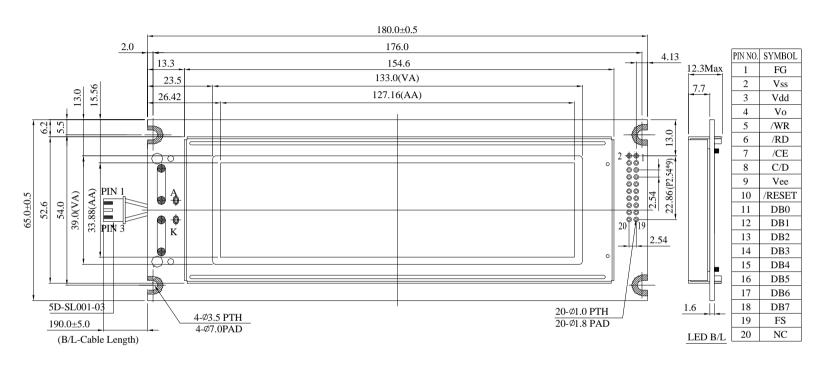
#### Definition of viewing angle( $CR \ge 2$ )

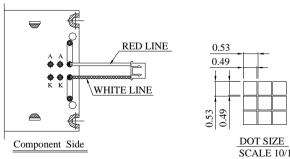


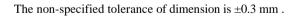
# **6.Interface Pin Function**

Pin No.	Symbol	Level	Description
1	FG	-	Frame ground ( Connected to bezel )
2	Vss	-	GND
3	Vdd	-	Power supply
4	Vo	-	Power supply for LCD driver
5	/WR	L	Data write. Write data into RA6963 when $WR = L$
6	/RD	L	Data read. Read data from RA6963 when $RD = L$
7	/CE	L	L : Chip enable
8	C/D	H/L	WR=L, C/D=H: Command Write C/D=L: Data write
			RD=L, C/D=H: Status Read C/D=L: Data read
9	Vee	-	Negative voltage output
10	/RESET	H/L	H : Normal ; L : Initialize RA6963
11	DB0	H/L	Data bus line
12	DB1	H/L	Data bus line
13	DB2	H/L	Data bus line
14	DB3	H/L	Data bus line
15	DB4	H/L	Data bus line
16	DB5	H/L	Data bus line
17	DB6	H/L	Data bus line
18	DB7	H/L	Data bus line
19	FS	H/L	Pins for selection of font; H : 6 * 8, L : 8 * 8
20	NC	-	No connection

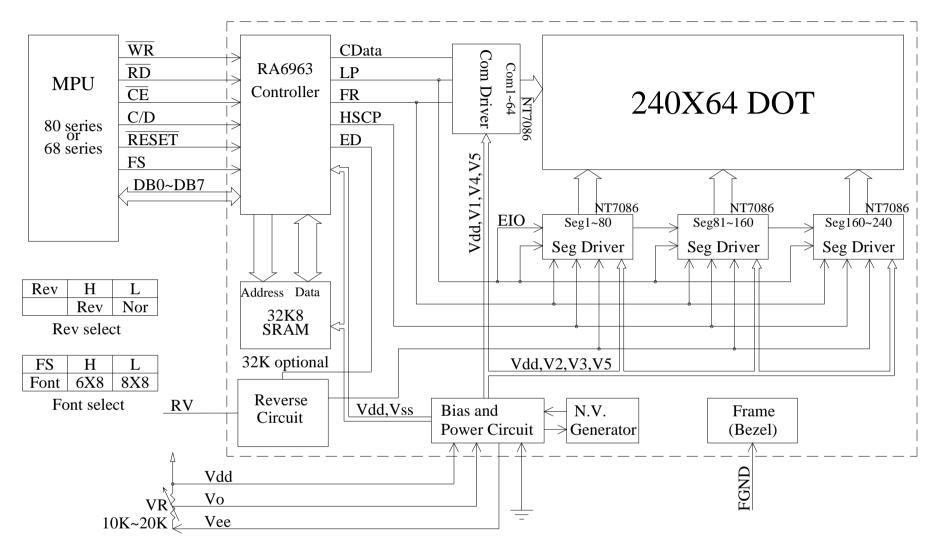
#### 7.Contour Drawing & Block Diagram











External contrast adjustment.

# 8.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

	<b>Environmental Test</b>		
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C ,90% RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation $-20^{\circ}C$ $25^{\circ}C$ $70^{\circ}C$ 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5k $\Omega$ CS=100pF 1 time	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

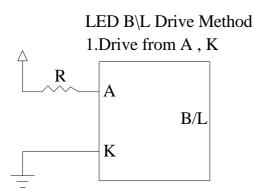
# **9.Backlight Information**

#### Specification

PARAMETER	SYMBOL	MIN	ТҮР	MAX	UNIT	TEST CONDITION
Supply Current	ILED	_	80	100	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	-
Reverse Voltage	VR	_	_	5	V	-
Luminance (Without LCD)	IV	520	650	_	CD/M <sup>2</sup>	ILED=80mA
LED Life Time (For Reference only)	_	_	50K	_	Hr.	ILED=80mA 25℃,50-60%RH, (Note 1)
Color	White		·			

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

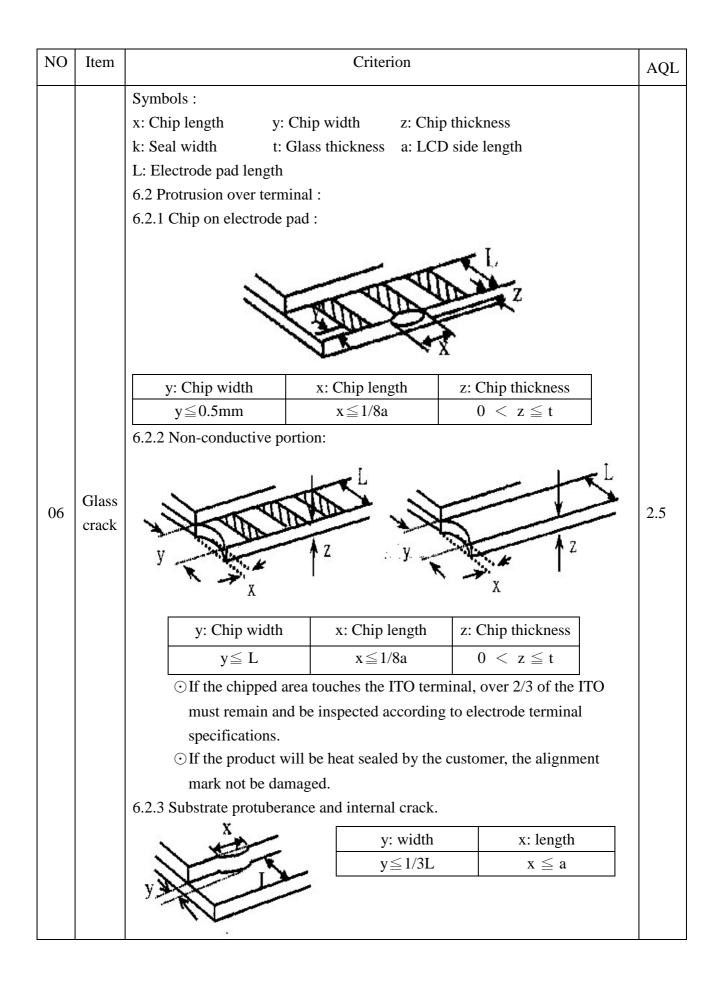
Note 1:50K hours is only an estimate for reference.



# **10.Inspection specification**

NO	Item			Criterion		AQL	
01	Electrical Testing Black or white spots on	<ul> <li>1.1 Missing vertical, horizontal segment, segment contrast defect.</li> <li>1.2 Missing character , dot or icon.</li> <li>1.3 Display malfunction.</li> <li>1.4 No function or no display.</li> <li>1.5 Current consumption exceeds product specifications.</li> <li>1.6 LCD viewing angle defect.</li> <li>1.7 Mixed product types.</li> <li>1.8 Contrast defect.</li> <li>2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present.</li> </ul>					
02	LCD (display only)		-	-	or lines within 3mm	2.5	
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type $\Phi = (x + y)$ $X$ $M$ $M$ $3.2 \text{ Line type : (}$	/2 ↓ ▼Y	SIZE	Acceptable Q TY Accept no dense 2 1 0 Acceptable Q TY Accept no dense 2 As round type	2.5	
04	Polarizer bubbles	If bubbles are vi judge using blac specifications, r to find, must ch specify direction	ck spot not easy eck in	Size $\Phi$ $\Phi \leq 0.20$ $0.20 < \Phi \leq 0.50$ $0.50 < \Phi \leq 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3 3	2.5	

NO	Item		Criterion		AQL
05	Scratches	Follow NO.3 LCD blac	k spots, white spots, con	tamination	
05	Scratches	Symbols Define:x: Chip lengthy:k: Seal widtht:L: Electrode pad length6.1 General glass chip :6.1.1 Chip on panel surf $6.1.1$ Chip on panel surf $1.1$ Chip thicknessz: Chip thickness $Z \le 1/2t$ $1/2t < z \le 2t$	Chip width z: Chi Glass thickness a: LCl	p thickness D side length panels: x: Chip length $x \le 1/8a$	2.5
		z: Chip thickness Z≦1/2t	y: Chip width Not over viewing	x: Chip length $x \le 1/8a$	
			area		
		$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	
		$\odot$ If there are 2 or more	chips, x is the total leng	th of each chip.	



NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	<ul> <li>8.1 Illumination source flickers when lit.</li> <li>8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards.</li> <li>8.3 Backlight doesn't light or color wrong.</li> </ul>	0.65 2.5 0.65
09	Bezel	<ul><li>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</li><li>9.2 Bezel must comply with job specifications.</li></ul>	2.5 0.65
10	PCB \ COB	<ul> <li>10.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li> <li>10.2 COB seal surface may not have pinholes through to the IC.</li> <li>10.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li> <li>10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.</li> <li>10.5 No oxidation or contamination PCB terminals.</li> <li>10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.</li> <li>10.7 The jumper on the PCB should conform to the product characteristic chart.</li> <li>10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.</li> <li>10.9 The Scraping testing standard for Copper Coating of PCB</li> </ul>	<ul> <li>2.5</li> <li>2.5</li> <li>0.65</li> <li>2.5</li> <li>0.65</li> <li>0.65</li> <li>2.5</li> <li>2.5</li> <li>2.5</li> <li>2.5</li> <li>2.5</li> </ul>
11	Soldering	<ul> <li>11.1 No un-melted solder paste may be present on the PCB.</li> <li>11.2 No cold solder joints, missing solder connections, oxidation or icicle.</li> <li>11.3 No residue or solder balls on PCB.</li> <li>11.4 No short circuits in components on PCB.</li> </ul>	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
NO 12	Item General appearance	Criterion 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened.	<ul> <li>2.5</li> <li>0.65</li> <li>2.5</li> <li>2.5</li> <li>2.5</li> <li>2.5</li> <li>2.5</li> </ul>
		<ul><li>12.7 Sealant on top of the ITO circuit has not hardened.</li><li>12.8 Pin type must match type in specification sheet.</li><li>12.9 LCD pin loose or missing pins.</li></ul>	0.65 0.65 0.65
		<ul><li>12.10 Product packaging must the same as specified on packaging specification sheet.</li><li>12.11 Product dimension and structure must conform to product specification sheet.</li></ul>	0.65
		12.12 Visual defect outside of VA is not considered to be rejection.	

# <u>11.Material List of Components for</u> <u>RoHs</u>

 AGTECHNOLOGIES Produtos Eletronicos, Ltd hereby declares that all of or part of products (with the mark"#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

- 2.Process for RoHS requirement :
  - (1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.
  - (2) Heat-resistance temp. :

Reflow :  $250^{\circ}$ C, 30 seconds Max. ;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. :  $235\pm5^{\circ}C$ ;

Recommended customer's soldering temp. of connector  $: 280^{\circ}$ C, 3 seconds.

## **12.Recommendable Storage**

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.